



July 1999
ADVANCE INFORMATION

FDD6030L

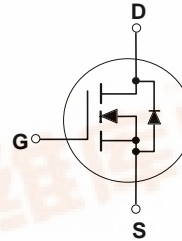
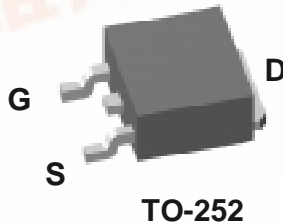
N-Channel Logic Level Enhancement Mode Field Effect Transistor

General Description

These N-Channel logic level enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage applications such as DC/DC converters and high efficiency switching circuits where fast switching, low in-line power loss, and resistance to transients are needed.

Features

- 50 A, 30 V. $R_{DS(ON)} = 0.0135 \Omega @ V_{GS} = 10 \text{ V}$
 $R_{DS(ON)} = 0.0200 \Omega @ V_{GS} = 4.5 \text{ V}$.
- Low gate charge.
- Fast switching speed.
- Low C_{rss} .



Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain-Source Voltage	30	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Maximum Drain Current -Continuous (Note 1)	50	A
	(Note 1a)	12	
	Maximum Drain Current -Pulsed	150	
P_D	Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ (Note 1)	60	W
	$T_A = 25^\circ\text{C}$ (Note 1a)	3.2	
	$T_A = 25^\circ\text{C}$ (Note 1b)	1.3	
T_J, T_{stg}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction-to- Case (Note 1)	2.1	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to- Ambient (Note 1a)	39	$^\circ\text{C/W}$
		96	$^\circ\text{C/W}$

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDD6030L	FDD6030L	13"	16mm	2500

Electrical Characteristics T_c=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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OFF CHARACTERISTICS

BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V			10	μA
I _{GSSF}	Gate-Body Leakage, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage, Reverse	V _{GS} = -20 V, V _{DS} = 0 V			-100	nA

ON CHARACTERISTICS (Note 2)

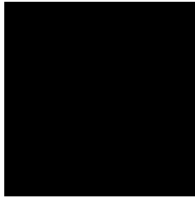
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	1		3	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 12 A V _{GS} = 4.5 V, I _D = 10 A			0.0135 0.0200	Ω


DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS


I _S	Maximum Continuous Drain-Source Diode Forward Current			2.7	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 2.7 A		1.2	V

Notes:

- R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the drain tab.
R_{θJC} is guaranteed by design while R_{θCA} is determined by the user's board design.



-  a) R_{θJA} = 40°C/W when mounted on a 1 in² pad of 2oz copper.

-  b) R_{θJA} = 96°C/W when mounted on a 0.076 in² pad of 2oz copper.

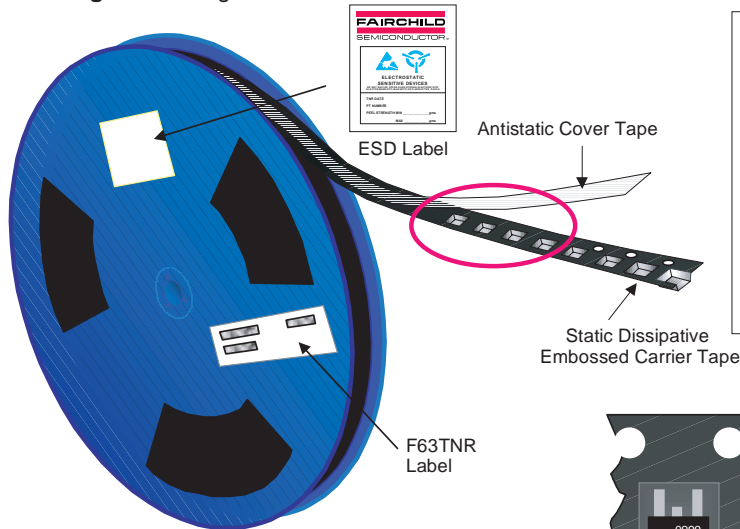
Scale 1 : 1 on letter size paper

- Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%

TO-252 Tape and Reel Data and Package Dimensions



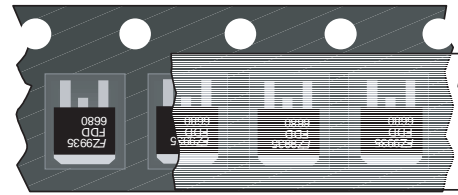
D-PAK (TO-252) Packaging Configuration: Figure 1.0



Packaging Description:

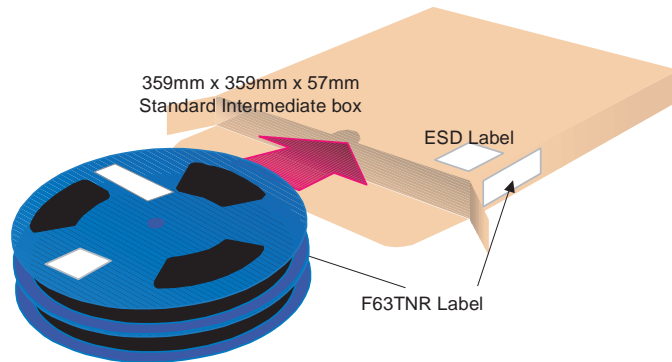
TO-252 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 2500 units per 13" or 330cm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). This and some other options are further described in the Packaging Information table.

These full reels are individually barcode labeled and placed inside a standard intermediate box (illustrated in figure 1.0) made of recyclable corrugated brown paper. One box contains two reels maximum. And these boxes are placed inside a barcode labeled shipping box which comes in different sizes depending on the number of parts shipped.



D-PAK (TO-252) Unit Orientation

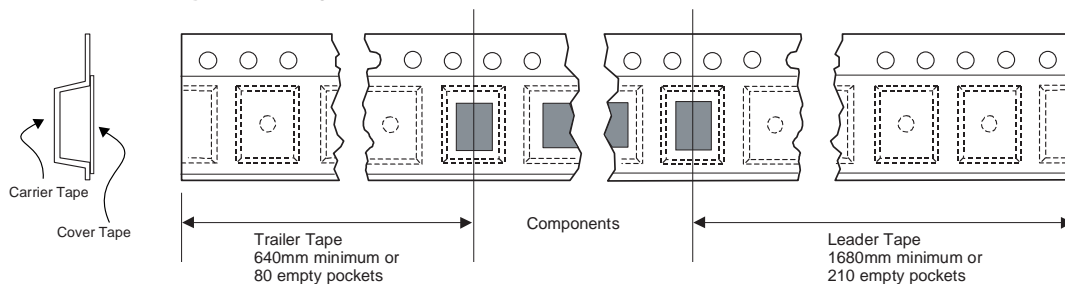
D-PAK (TO-252) Packaging Information	
Packaging Option	Standard (no flow code)
Packaging type	TNR
Qty per Reel/Tube/Bag	2,500
Reel Size	13" Dia
Box Dimension (mm)	359x359x57
Max qty per Box	5,000
Weight per unit (gm)	0.300
Weight per Reel(kg)	1.200
Note/Comments	



F63TNR Label sample

LOT: CBVK741B019	QTY: 2500
FSID: FDD6680	SPEC:
D/C1: Z9942	QTY1:
D/C2:	QTY2:
SPEC REV:	CPN:
N/F: F	(F63TNR)3

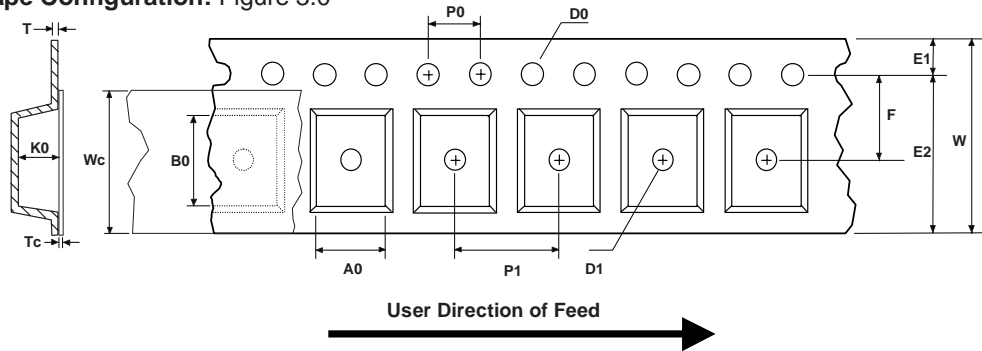
TO-252 (D-PAK) Tape Leader and Trailer Configuration: Figure 2.0



TO-252 Tape and Reel Data and Package Dimensions

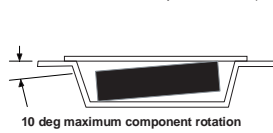
D-PAK (TO-252) Embossed Carrier

Tape Configuration: Figure 3.0

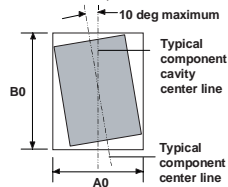


Dimensions are in millimeter														
Pkg type	A0	B0	W	D0	D1	E1	E2	F	P1	P0	K0	T	Wc	Tc
TO252 (24mm)	6.90 +/-0.10	10.50 +/-0.10	16.0 +/-0.3	1.55 +/-0.05	1.5 +/-0.10	1.75 +/-0.10	14.25 min	7.50 +/-0.10	8.0 +/-0.1	4.0 +/-0.1	2.65 +/-0.10	0.30 +/-0.05	13.0 +/-0.3	0.06 +/-0.02

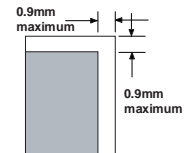
Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation

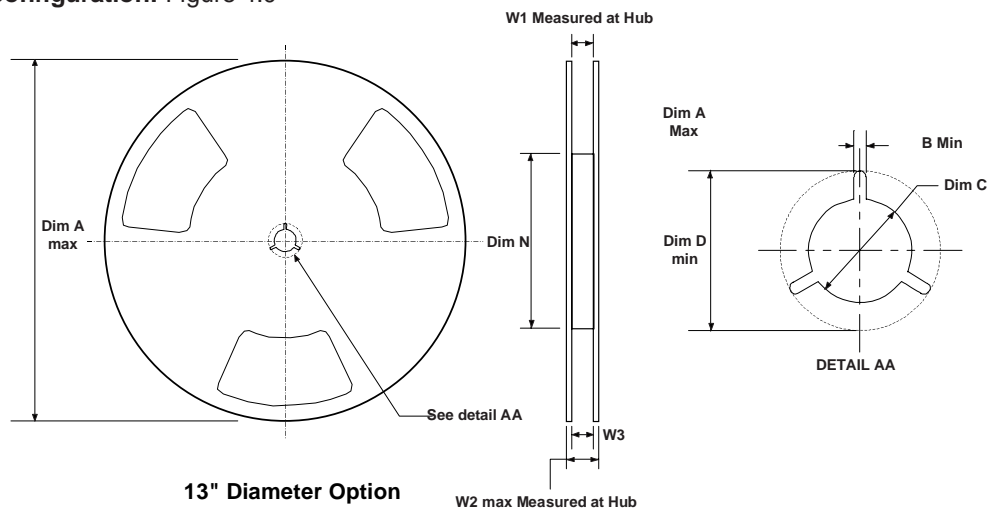


Sketch B (Top View)
Component Rotation



Sketch C (Top View)
Component lateral movement

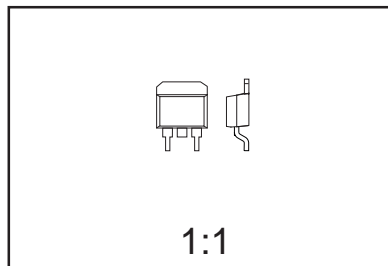
D-PAK (TO-252) Reel Configuration: Figure 4.0



Dimensions are in inches and millimeters									
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
164mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.646 +0.078/-0.000 16.4 +2/0	0.882 22.4	0.626 - 0.764 15.9 - 19.4

TO-252 Tape and Reel Data and Package Dimensions

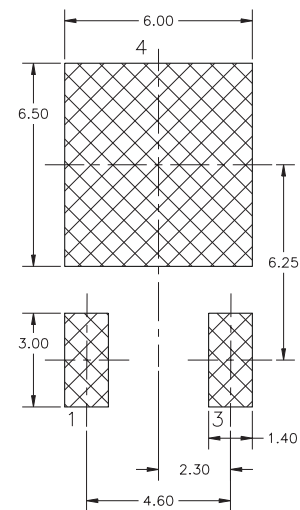
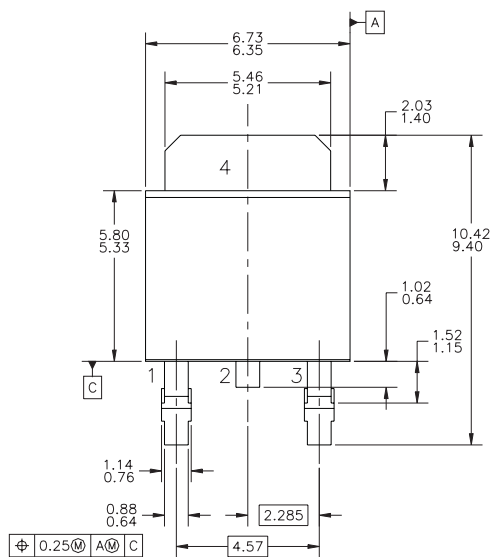
TO-252 (FS PKG Code AA)



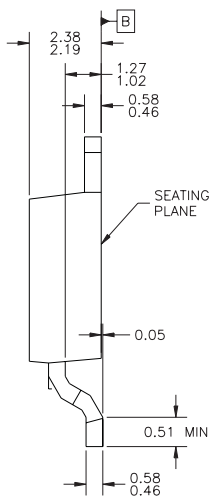
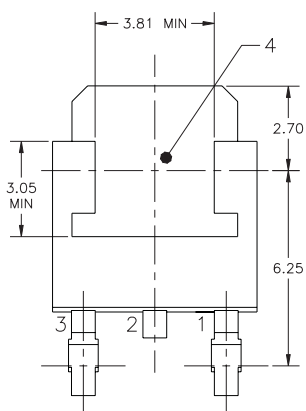
Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.300



LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

A) ALL DIMENSIONS ARE IN MILLIMETERS.

B) THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE B, VARIATION AB, ITEM 10.268, DATED SEPTEMBER 1988.

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